

ABSTRACT

Provided is a cup-shaped plating apparatus which can plate the whole area of a plating target surface with a uniform film thickness. In a cup-shaped plating apparatus including a placement portion of an object to be plated which is provided at an opening end of a plating tank, means for supplying a plating solution into the plating tank, a plating solution outlet port which is formed in the plating tank, a cavity portion into which the plating solution which has flown out of the outlet port flows, a plating solution discharge port within the cavity portion, and a collection tank for the plating solution discharged from the discharge port, which subjects the object to be plated to plating treatment while supplying the plating solution into the plating tank, the shape and/or opening area of the discharge port formed on the downstream side of the cavity portion can be changed. If the shape and/or opening area of the discharge port formed on the downstream side of the cavity portion can be adjusted, it is possible to suppress nonuniform plating and variations in plating on a plating target surface by adjusting the shape and/or opening area.



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